

MATERIALS

HOUSING: HI-TEMP. PLASTIC (UL 94V-0), BLACK
 SOLDER PAD: COPPER ALLOY, TIN PLATING
 TERMINAL: COPPER ALLOY, GOLD PLATED ON CONTACT AREA
 TIN PLATING ON SOLDER TAIL

SPECIFICATION

CURRENT RATING: 1.2 AMP MAX
 DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE
 CONTACT RESISTANCE: 25m OHMS
 INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V
 OPERATION TEMPERATURE: -55°C~+125°C

PART NUMBER:

ASMBA - * * * T - 2 2 2

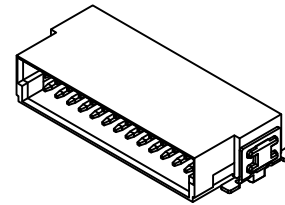
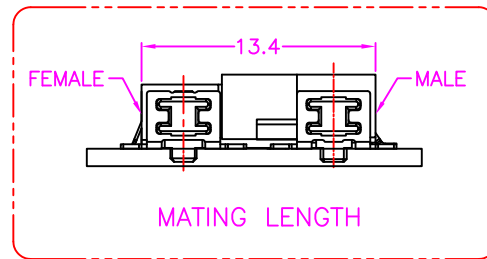
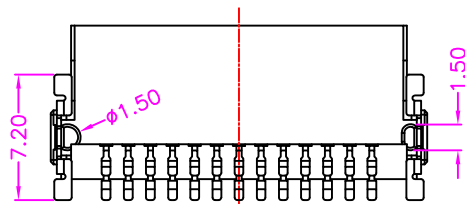


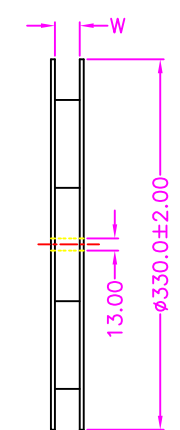
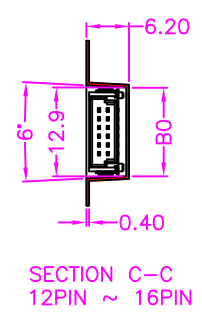
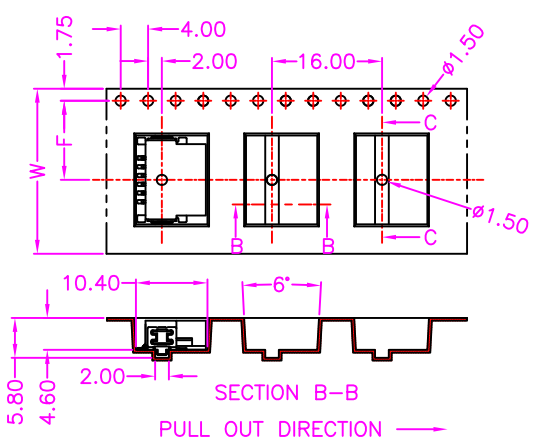
CONTACT PLATED OPTION

- 1: GOLD FLASH
- 3: 3u" GOLD
- 5: 5u" GOLD
- 6: 10u" GOLD
- 7: 15u" GOLD
- 9: 30u" GOLD

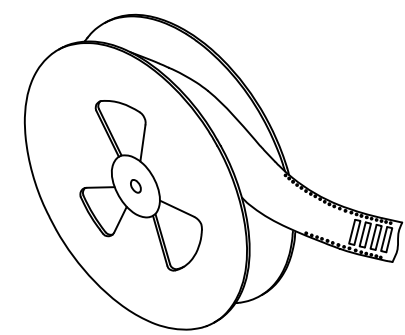
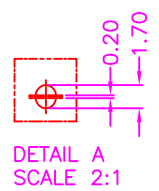
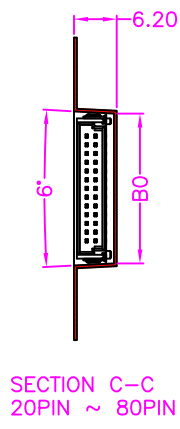
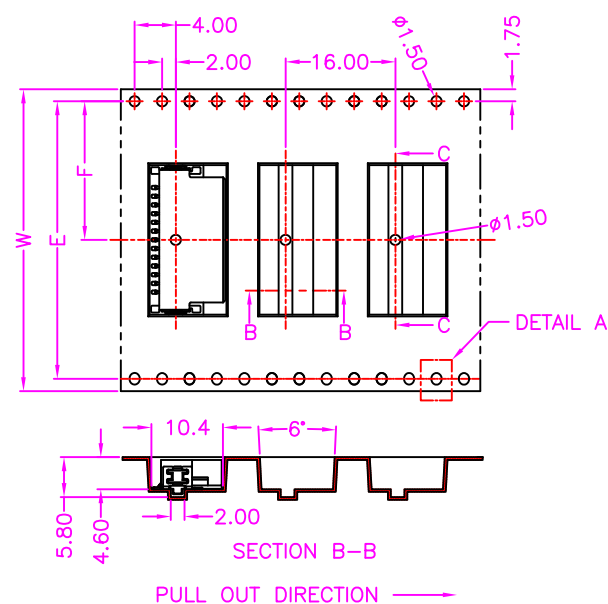
TABLE

POS.	DIM A	DIM B	DIM C	DIM D	DIM E	DIM F	DIM G
12	12.70	11.34	10.77	10.37	9.57	8.57	6.35
16	15.24	13.88	13.31	12.91	12.11	11.11	8.89
20	17.78	16.42	15.85	15.45	14.65	13.65	11.43
26	21.59	20.23	19.66	19.26	18.46	17.46	15.24
30	24.13	22.77	22.20	21.80	21.00	20.00	17.78
32	25.40	24.04	23.47	23.07	22.27	21.27	19.05
40	30.48	29.12	28.55	28.15	27.35	26.35	24.13
50	36.83	35.47	34.90	34.50	33.70	32.70	30.48
68	48.26	46.90	46.33	45.93	45.13	44.13	41.91
80	55.88	54.52	53.95	53.55	52.75	51.75	49.53





POS.	PCS/PER REEL	REEL/OUTSIDE CTN	PCS/OUTSIDE CTN	CTN SIZE
12	600	7	4200	350*350*260
16				
20				
24		5	3000	
26				
30		4	2400	
32				
40	3	1800		
50				
68	5	3000	350*350*460	
80				



POS.	B0±0.15	F±0.10	E±0.10	W ^{+0.30} _{-0.10}
12P	12.90	11.50	24.00	24.00
16P				
20P	18.00	14.20	28.40	32.00
24P				
26P	21.79	20.20	40.40	44.00
30P				
32P	37.03	26.20	52.40	56.00
40P				
50P	48.46	34.20	68.40	72.00
68P				
80P	56.08			